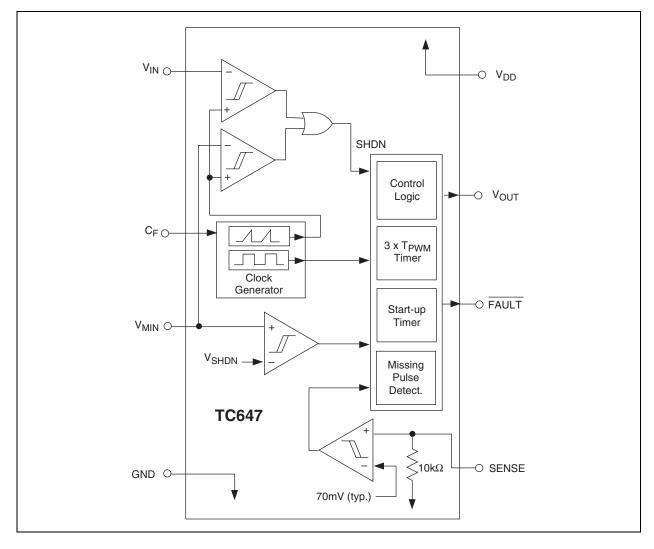
# **Functional Block Diagram**



# 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings\***

Supply Voltage6V					
Input Voltage, Any Pin (GND – 0.3V) to ( $V_{DD}$ +0.3V)					
Package Thermal Resistance: PDIP (R <sub>0.IA</sub> )125°C/W					
SOIC (R <sub>0JA</sub> )					
Specified Temperature Range40°C to +125°C					
Storage Temperature Range65°C to +150°C					

#### DC ELECTRICAL SPECIFICATIONS

\*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
V <sub>DD</sub>	Supply Voltage	3.0	—	5.5	V	
I <sub>DD</sub>	Supply Current, Operating	-	0.5	1	mA	Pins 6, 7 Open, C <sub>F</sub> = 1 $\mu$ F, V <sub>IN</sub> = V <sub>C(MAX</sub>
I <sub>DD(SHDN)</sub>	Supply Current, Shutdown Mode	_	25	—	μA	Pins 6, 7 Open, C <sub>F</sub> = 1 μF, V <sub>MIN</sub> = 0.35V
I <sub>IN</sub>	V <sub>IN</sub> , V <sub>MIN</sub> Input Leakage	- 1.0	—	+1.0	μA	Note 1
V <sub>OUT</sub> Output						
t <sub>R</sub>	V <sub>OUT</sub> Rise Time	_	_	50	µsec	I <sub>OH</sub> = 5 mA, <b>Note 1</b>
t <sub>F</sub>	V <sub>OUT</sub> Fall Time	—	_	50	µsec	I <sub>OL</sub> = 1 mA, <b>Note 1</b>
t <sub>SHDN</sub>	Pulse Width (On V <sub>MIN</sub> ) to Clear Fault Mode	30	_	—	µsec	V <sub>SHDN</sub> , V <sub>HYST</sub> Specifications, <b>Note 1</b>
I <sub>OL</sub>	Sink Current at V <sub>OUT</sub> Output	1.0	—	_	mA	$V_{OL}$ = 10% of $V_{DD}$
I <sub>ОН</sub>	Source Current at VOUT Output	5.0	-	—	mA	$V_{OH}$ = 80% of $V_{DD}$
V <sub>IN</sub> , V <sub>MIN</sub> Inputs						
V <sub>C(MAX)</sub>	Input Voltage at V <sub>IN</sub> or V <sub>MIN</sub> for 100% PWM Duty Cycle	2.5	2.65	2.8	V	
V <sub>C(SPAN)</sub>	V <sub>C(MAX)</sub> - V <sub>C(MIN)</sub>	1.3	1.4	1.5	V	
V <sub>SHDN</sub>	Voltage Applied to V <sub>MIN</sub> to Ensure Shutdown Mode	_	_	V <sub>DD</sub> x 0.13	V	
V <sub>REL</sub>	Voltage Applied to V <sub>MIN</sub> to Release Shutdown Mode	V <sub>DD</sub> x 0.19	_	—	V	V <sub>DD</sub> = 5V
Pulse Width Mo	dulator					
F <sub>PWM</sub>	PWM Frequency	26	30	34	Hz	C <sub>F</sub> = 1.0 μF
SENSE Input				1		-
V <sub>TH(SENSE)</sub>	SENSE Input Threshold Voltage with Respect to GND	50	70	90	mV	Note 1
FAULT Output						
V <sub>OL</sub>	Output Low Voltage	_	_	0.3	V	I <sub>OL</sub> = 2.5 mA
t <sub>MP</sub>	Missing Pulse Detector Timer	—	32/F	—	Sec	
t <sub>STARTUP</sub>	Start-up Timer	_	32/F	_	Sec	
t <sub>DIAG</sub>	Diagnostic Timer	_	3/F	_	Sec	

Note 1: Ensured by design, not tested.

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# 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

Pin No.	Symbol	Description				
1	V <sub>IN</sub>	Analog Input				
2	C <sub>F</sub>	Analog Output				
3	V <sub>MIN</sub>	Analog Input				
4	GND	Ground Terminal				
5	SENSE	Analog Input				
6	FAULT	Digital (Open Collector) Output				
7	V <sub>OUT</sub>	Digital Output				
8	V <sub>DD</sub>	Power Supply Input				

TABLE 2-1: PIN FUNCTION TABLE

## 2.1 Analog Input (V<sub>IN</sub>)

The thermistor network (or other temperature sensor) connects to the V<sub>IN</sub> input. A voltage range of 1.25V to 2.65V (typical) on this pin drives an active duty cycle of 0% to 100% on the V<sub>OUT</sub> pin.

# 2.2 Analog Output (C<sub>F</sub>)

 $C_F$  is the positive terminal for the PWM ramp generator timing capacitor. The recommended  $C_F$  is 1  $\mu F$  for 30 Hz PWM operation.

# 2.3 Analog Input (V<sub>MIN</sub>)

An external resistor divider connected to the V<sub>MIN</sub> input sets the minimum fan speed by fixing the minimum PWM duty cycle (1.25V to 2.65V = 0% to 100%, typical). The TC647 enters shutdown mode when V<sub>MIN</sub>  $\leq$  V<sub>SHDN</sub>. During shutdown, the FAULT output is inactive and supply current falls to 25 µA (typical). The TC647 exits shutdown mode when V<sub>MIN</sub>  $\geq$  V<sub>REL</sub>. See Section 5.0, "Typical Applications", for more details.

## 2.4 Ground (GND)

GND denotes the ground terminal.

## 2.5 Analog Input (SENSE)

Pulses are detected at the SENSE pin as fan rotation chops the current through a sense resistor. The absence of pulses indicates a fault.

# 2.6 Digital Output (FAULT)

The  $\overline{FAULT}$  line goes low to indicate a fault condition. When  $\overline{FAULT}$  goes low due to a fan fault condition, the device is latched in shutdown mode until deliberately cleared or until power is cycled. FAULT may be connected to V<sub>MIN</sub> if a hard shutdown is desired.

# 2.7 Digital Output (V<sub>OUT</sub>)

V<sub>OUT</sub> is an active high complimentary output that drives the base of an external NPN transistor (via an appropriate base resistor) or the gate of an N-channel MOS-FET. This output has asymmetrical drive (see Section 1.0, "Electrical Characteristics").

# 2.8 Power Supply Input (V<sub>DD</sub>)

 $V_{DD}$  may be independent of the fan's power supply (see Section 1.0, "Electrical Characteristics").

# 3.0 DETAILED DESCRIPTION

## 3.1 PWM

The PWM circuit consists of a ramp generator and threshold detector. The frequency of the PWM is determined by the value of the capacitor connected to the C<sub>F</sub> input. A frequency of 30 Hz is recommended (C<sub>F</sub> = 1  $\mu$ F). The PWM is also the time base for the Start-up Timer (see Section 3.3, "Start-Up Timer"). The PWM voltage control range is 1.25V to 2.65V (typical) for 0% to 100% output duty cycle.

# 3.2 V<sub>OUT</sub> Output

The V<sub>OUT</sub> pin is designed to drive a low cost transistor or MOSFET as the low side power switching element in the system. Various examples of driver circuits will be shown throughout this data sheet. This output has an asymmetric complimentary drive and is optimized for driving NPN transistors or N-channel MOSFETs. Since the system relies on PWM rather than linear control, the power dissipation in the power switch is kept to a minimum. Generally, very small devices (TO-92 or SOT packages) will suffice.

# 3.3 Start-Up Timer

To ensure reliable fan start-up, the Start-up Timer turns the V<sub>OUT</sub> output on for 32 cycles of the PWM whenever the fan is started from the off state. This occurs at power up and when coming out of shutdown mode. If the PWM frequency is 30 Hz (C<sub>F</sub> = 1  $\mu$ F), the resulting start-up time will be approximately one second. If a fault is detected, the Diagnostic Timer is triggered once, followed by the Start-up Timer. If the fault persists, the device is shut down (see Section 3.6, "FAULT Output").

# 3.4 Shutdown Control (Optional)

If  $V_{MIN}$  (Pin 3) is pulled below  $V_{SHDN}$ , the TC647 will go into shutdown mode. This can be accomplished by driving  $V_{MIN}$  with an open-drain logic signal or using an external transistor, as shown in Figure 3-1. All functions are suspended until the voltage on  $V_{MIN}$  becomes higher than  $V_{REL}$  (0.85V @  $V_{DD}$  = 5.0V). Pulling  $V_{MIN}$ below  $V_{SHDN}$  will always result <u>in complete device</u> shutdown and reset. The FAULT output is unconditionally inactive in shutdown mode.

A small amount of hysteresis, typically one percent of  $V_{DD}$  (50 mV at  $V_{DD}$  = 5.0V), is designed into the  $V_{SHDN}/V_{REL}$  threshold. The levels specified for  $V_{SHDN}$  and  $V_{REL}$  in Section 1.0, "Electrical Characteristics", include this hysteresis plus adequate margin to account for normal variations in the absolute value of the threshold and hysteresis.

**CAUTION:** Shutdown mode is unconditional. That is, the fan will not be activated regardless of the voltage at  $V_{IN}$ . The fan should not be shut down until all heat producing activity in the system is at a negligible level.

## 3.5 SENSE Input (FanSense<sup>™</sup> Technology)

The SENSE input (Pin 5) is connected to a low value current sensing resistor in the ground return leg of the fan circuit. During normal fan operation, commutation occurs as each pole of the fan is energized. This causes brief interruptions in the fan current, seen as pulses across the sense resistor. If the device is not in shutdown mode, and pulses are not appearing at the SENSE input, a fault exists.

The short, rapid change in fan current (high dl/dt) causes a corresponding dV/dt across the sense resistor,  $R_{SENSE}$ . The waveform on  $R_{SENSE}$  is differentiated and converted to a logic-level, pulse-train by  $C_{SENSE}$  and the internal signal processing circuitry. The presence and frequency of this pulse-train is a direct indication of fan operation. See Section 5.0, "Typical Applications", for more details.

# 3.6 FAULT Output

Pulses appearing at SENSE due to the PWM turning on are blanked with the remaining pulses being filtered by a missing pulse detector. If consecutive pulses are not detected for 32 PWM cycles ( $\equiv$ 1 Sec if C<sub>F</sub> = 1 µF), the Diagnostic Timer is activated and V<sub>OUT</sub> is driven high continuously for three PWM cycles ( $\cong$ 100 msec if C<sub>F</sub> = 1 µF). If a pulse is not detected within this window, the Start-up Timer is triggered (see Section 3.3, "Start-Up Timer"). This should clear a transient fault condition. If the missing pulse detector times out again, the PWM is stopped and FAULT goes low. When FAULT is activated due to this condition, the device is latched in shutdown mode and will remain off indefinitely.

**Note:** At this point, action must be taken to restart the fan by momentarily pulling  $V_{MIN}$  below  $V_{SHDN}$ , or cycling system power. In either case, the fan cannot remain disabled due to a fault condition as severe system damage could result. If the fan cannot be restarted, the system should be shut down.

The TC647 may be configured to continuously attempt fan restarts, if so desired.

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Continuous restart mode is enabled by connecting the FAULT output to V<sub>MIN</sub> through a 0.1  $\mu$ F capacitor, as shown in Figure 3-1. When so connected, the TC647 automatically attempts to restart the fan whenever a fault condition occurs. When the FAULT output is driven low, the V<sub>MIN</sub> input is momentarily pulled below V<sub>SHDN</sub>, initiating a reset and clearing the fault

condition. Normal fan start-up is then attempted as previously described. The FAULT output may be connected to external logic (or the interrupt input of a microcontroller) to shut the TC647 down if multiple fault pulses are detected at approximately one second intervals.

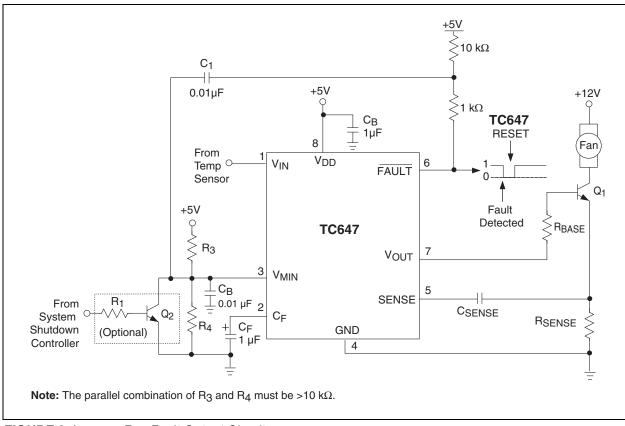


FIGURE 3-1: Fan Fault Output Circuit.

## 4.0 SYSTEM BEHAVIOR

The flowcharts describing the TC647's behavioral algorithm are shown in Figure 4-1. They can be summarized as follows:

### 4.1 Power-Up

- (1) Assuming the device is not being held in shutdown mode ( $V_{MIN} > V_{REL}$ )...
- (2) Turn V<sub>OUT</sub> output on for 32 cycles of the PWM clock. This ensures that the fan will start from a dead stop.
- (3) During this Start-up Timer, if a fan pulse is detected, branch to Normal Operation; if none are received...
- (4) Activate the 32-cycle Start-up Timer one more time and look for fan pulse; if a fan pulse is detected, proceed to Normal Operation; if none are received...
- (5) Proceed to Fan Fault.
- (6) End.

## 4.2 Normal Operation

Normal Operation is an endless loop which may only be exited by entering shutdown mode or Fan Fault. The loop can be thought of as executing at the frequency of the oscillator and PWM.

- (1) Reset the missing pulse detector.
- (2) Is TC647 in shutdown? If so ...
  - a. V<sub>OUT</sub> duty cycle goes to zero.
  - b. FAULT is disabled.
  - c. Exit the loop and wait for V<sub>MIN</sub> > V<sub>REL</sub> to resume operation (indistinguishable from Power-up).
- (3) Drive V<sub>OUT</sub> to a duty cycle proportional to greater of V<sub>IN</sub> and V<sub>MIN</sub> on a cycle by cycle basis.
- (4) If a fan pulse is detected, branch back to the start of the loop (1).
- (5) If the missing pulse detector times out ...
- (6) Activate the 3-cycle Diagnostic Timer and look for pulses; if a fan pulse is detected, branch back to the start of the loop (1); if none are received...
- (7) Activate the 32-cycle Start-up Timer and look for pulses; if a fan pulse is detected, branch back to the start of the loop (1); if none are received...
- (8) Quit Normal Operation and go to Fan Fault.
- (9) End.

## 4.3 Fan Fault

Fan Fault is an infinite loop wherein the TC647 is latched in shutdown mode. This mode can only be released by a reset (i.e.,  $V_{MIN}$  being brought below  $V_{SHDN}$ , then above  $V_{REL}$ , or by power cycling).

- While in this state, FAULT is latched on (low) and the V<sub>OUT</sub> output is disabled.
- (2) A reset sequence applied to the V<sub>MIN</sub> pin will exit the loop to Power-up.
- (3) End.

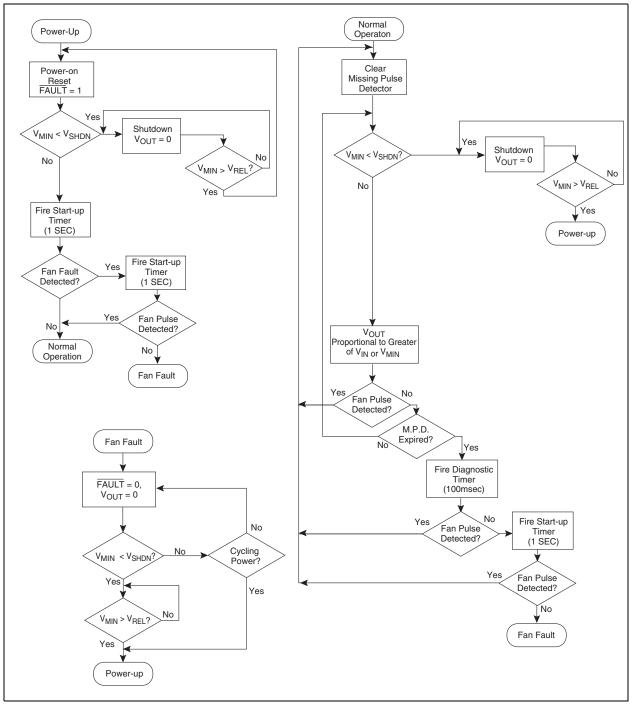


FIGURE 4-1:

TC647 Behavioral Algorithm Flowchart.

DS21447C-page 8

# 5.0 TYPICAL APPLICATIONS

Designing with the TC647 involves the following:

- (1) The temp sensor network must be configured to deliver 1.25V to 2.65V on  $V_{\rm IN}$  for 0% to 100% of the temperature range to be regulated.
- (2) The minimum fan speed (V\_{MIN}) must be set.
- (3) The output drive transistor and associated circuitry must be selected.
- (4) The SENSE network, R<sub>SENSE</sub> and C<sub>SENSE</sub>, must be designed for maximum efficiency while delivering adequate signal amplitude.
- (5) If shutdown capability is desired, the drive requirements of the external signal or circuit must be considered.

The TC642 demonstration and prototyping board (TC642DEMO) and the TC642 Evaluation Kit (TC642EV) provide working examples of TC647 circuits and prototyping aids. The TC642DEMO is a printed circuit board optimized for small size and ease of inclusion into system prototypes. The TC642EV is a larger board intended for benchtop development and analysis. At the very least, anyone contemplating a design using the TC647 should consult the documentation for both TC642EV and (DS21403) and TC642DEMO (DS21401). Figure 5-1 shows the base schematic for the TC642DEMO.

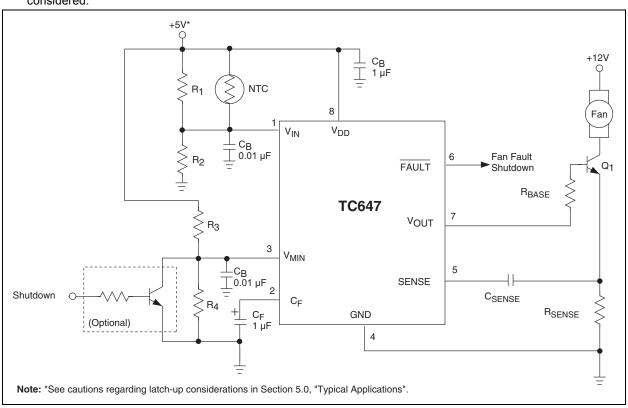


FIGURE 5-1: Typical Application Circuit.

## 5.1 Temperature Sensor Design

The temperature signal connected to  $V_{\text{IN}}$  must output a voltage in the range of 1.25V to 2.65V (typical) for 0% to 100% of the temperature range of interest. The circuit in Figure 5-2 illustrates a convenient way to provide this signal.

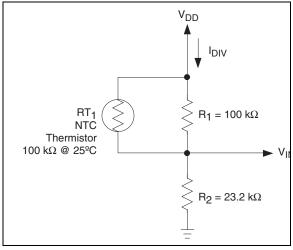


FIGURE 5-2: Temperature Sensing Circuit.

Figure 5-2 illustrates a simple temperature dependent voltage divider circuit.  $RT_1$  is a conventional 100 k $\Omega$  @ 25°C NTC thermistor, while R1 and R2 are standard resistors. The supply voltage, V<sub>DD</sub>, is divided between R2 and the parallel combination of RT1 and R1 (for convenience, the parallel combination of RT1 and R1 will be referred to as R<sub>TEMP</sub>). The resistance of the thermistor at various temperatures is obtained from the manufacturer's specifications. Thermistors are often referred to in terms of their resistance at 25°C. Generally, the thermistor shown in Figure 5-2 is a non-linear device with a negative temperature coefficient (also called an NTC thermistor). In Figure 5-2, R1 is used to linearize the thermistor temperature response and R<sub>2</sub> is used to produce a positive temperature coefficient at the V<sub>IN</sub> node. As an added benefit, this configuration produces an output voltage delta of 1.4V, which is well within the range of the  $V_{C(SPAN)}$  specification of the TC647. A 100 k $\Omega$  NTC thermistor is selected for this application in order to keep I<sub>DIV</sub> at a minimum.

For the voltage range at V<sub>IN</sub> to be equal to 1.25V to 2.65V, the temperature range of this configuration is 0°C to 50°C. If a different temperature range is required from this circuit, R<sub>1</sub> should be chosen to equal the resistance value of the thermistor at the center of this new temperature range. It is suggested that a maximum temperature range of 50°C be used with this circuit due to thermistor linearity limitations. With this change, R<sub>2</sub> is adjusted according to the following equations:

#### EQUATION

$$\frac{V_{DD} x R_2}{R_{TEMP} (T_1) + R_2} = V(T_1)$$
$$\frac{V_{DD} x R_2}{R_{TEMP} (T_2) + R_2} = V(T_2)$$

Where  $T_1$  and  $T_2$  are the chosen temperatures and  $R_{TEMP}$  is the parallel combination of the thermistor and  $R_1$ .

These two equations facilitate solving for the two unknown variables,  $R_1$  and  $R_2$ . More information about Thermistors may be obtained from AN679, *"Temperature Sensing Technologies"*, and AN685, *"Thermistors in Single Supply Temperature Sensing Circuits"*, which can be downloaded from Microchip's website at www.microchip.com.

### 5.2 Minimum Fan Speed

A voltage divider on V<sub>MIN</sub> sets the minimum PWM duty cycle and, thus, the minimum fan speed. As with the V<sub>IN</sub> input, 1.25V to 2.65V corresponds to 0% to 100% duty cycle. Assuming that fan speed is linearly related to duty cycle, the minimum speed voltage is given by the equation:

#### EQUATION

$$V_{MIN} = rac{Minimum Speed}{Full Speed} x (1.4V) + 1.25V$$

For example, if 2500 RPM equates to 100% fan speed, and a minimum speed of 1000 RPM is desired, then the  $V_{\text{MIN}}$  voltage is:

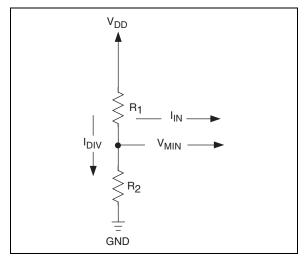
#### EQUATION

$$V_{MIN} = \frac{1000}{2500} x (1.4V) + 1.25V = 1.81V$$

The V<sub>MIN</sub> voltage may be set using a simple resistor divider as shown in Figure 5-3. Per Section 1.0, "Electrical Characteristics", the leakage current at the V<sub>MIN</sub> pin is no more than 1  $\mu$ A. It would be very conservative to design for a divider current, I<sub>DIV</sub>, of 100  $\mu$ A. If V<sub>DD</sub> = 5.0V then;

#### EQUATION

$$I_{DIV} = 1e^{-4}A = \frac{5.0V}{R_1 + R_2}, \text{ therefore}$$
$$R_1 + R_2 = \frac{5.0V}{1e^{-4}A} = 50,000 \ \Omega = 50 \ k\Omega$$





We can further specify  $R_1$  and  $R_2$  by the condition that the divider voltage is equal to our desired  $V_{MIN}$ . This yields the following equation:

V<sub>MIN</sub> Circuit.

#### EQUATION

$$V_{MIN} = \frac{V_{DD} \, x \, R_2}{R_1 + R_2}$$

Solving for the relationship between  $R_1$  and  $R_2$  results in the following equation:

#### EQUATION

$$R_1 = R_2 x \qquad \frac{V_{DD} - V_{MIN}}{V_{MIN}}$$

In this example,  $R_1 = (1.762) R_2$ . Substituting this relationship back into the previous equation yields the resistor values:

$$R_2 = 18.1 \text{ k}\Omega$$
  
 $R_1 = 31.9 \text{ k}\Omega$ 

In this case, the standard values of 31.6 k $\Omega$  and 18.2 k $\Omega$  are very close to the calculated values and would be more than adequate.

## 5.3 Operations at Low Duty Cycle

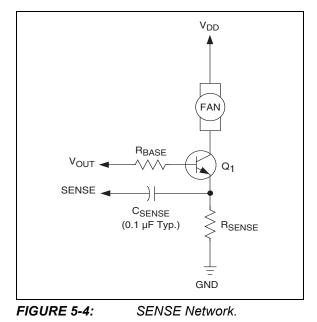
One boundary condition which may impact the selection of the minimum fan speed is the irregular activation of the Diagnostic Timer due to the TC647 "missing" fan commutation pulses at low speeds. This is a natural consequence of low PWM duty cycles (typically 25% or less). Recall that the SENSE function detects commutation of the fan as disturbances in the current through R<sub>SENSE</sub>. These can only occur when the fan is energized (i.e., V<sub>OUT</sub> is "on"). At very low duty cycles, the

 $V_{OUT}$  output is "off" most of the time. The fan may be rotating normally, but the commutation events are occurring during the PWM's off-time.

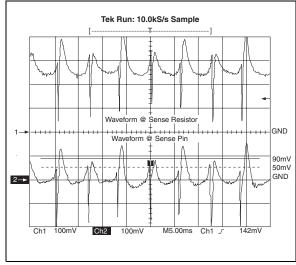
The phase relationship between the fan's commutation and the PWM edges tends to "walk around" as the system operates. At certain points, the TC647 may fail to capture a pulse within the 32-cycle missing pulse detector window. When this happens, the 3-cycle Diagnostic Timer will be activated, the V<sub>OUT</sub> output will be active continuously for three cycles and, if the fan is operating normally, a pulse will be detected. If all is well, the system will return to normal operation. There is no harm in this behavior, but it may be audible to the user as the fan will accelerate briefly when the Diagnostic Timer fires. For this reason, it is recommended that V<sub>MIN</sub> be set no lower than 1.8V.

# 5.4 FanSense<sup>™</sup> Network (R<sub>SENSE</sub> and C<sub>SENSE</sub>)

The FanSense network, comprised of R<sub>SENSE</sub> and C<sub>SENSE</sub>, allows the TC647 to detect commutation of the fan motor (FanSense™ technology). This network can be thought of as a differentiator and threshold detector. The function of  $\mathsf{R}_{\mathsf{SENSE}}$  is to convert the fan current into a voltage.  $\mathsf{C}_{\mathsf{SENSE}}$  serves to AC-couple this voltage signal and provide a ground referenced input to the SENSE pin. Designing a proper SENSE network is simply a matter of scaling R<sub>SENSE</sub> to provide the necessary amount of gain (i.e., the current-to-voltage conversion ratio). A 0.1 µF ceramic capacitor is recommended for  $\mathsf{C}_{\mathsf{SENSE}}.$  Smaller values require larger sense resistors, and higher value capacitors are bulkier and more expensive. Using a 0.1 µF results in reasonable values for R<sub>SENSE</sub>. Figure 5-4 illustrates a typical SENSE network. Figure 5-5 shows the waveforms observed using a typical SENSE network.



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#### FIGURE 5-5: SENSE Waveforms.

Table 5-1 lists the recommended values of  $R_{SENSE}$  based on the nominal operating current of the fan. Note that the current draw specified by the fan manufacturer may be a worst-case rating for near-stall conditions and not the fan's nominal operating current. The values in Table 5-1 refer to actual average operating current. If the fan current falls between two of the values listed, use the higher resistor value. The end result of employing Table 5-1 is that the signal developed across the sense resistor is approximately 450 mV in amplitude.

Nominal Fan Current (mA)	R <sub>SENSE</sub> (Ω)
50	9.1
100	4.7
150	3.0
200	2.4
250	2.0
300	1.8
350	1.5
400	1.3
450	1.2
500	1.0

TABLE 5-1: R<sub>SENSE</sub> VS. FAN CURRENT

## 5.5 Output Drive Transistor Selection

The TC647 is designed to drive an external transistor or MOSFET for modulating power to the fan. This is shown as  $Q_1$  in Figures 3-1, 5-1, 5-4, 5-6, 5-7, 5-8 and 5-9. The V<sub>OUT</sub> pin has a minimum source current of 5 mA and a minimum sink current of 1 mA. Bipolar transistors or MOSFETs may be used as the power switching element, as shown in Figure 5-7. When high current gain is needed to drive larger fans, two transistors may be used in a Darlington configuration. These circuit topologies are shown in Figure 5-7: (a) shows a single NPN transistor used as the switching element; (b) illustrates the Darlington pair; and (c) shows an Nchannel MOSFET.

One major advantage of the TC647's PWM control scheme versus linear speed control is that the power dissipation in the pass element is kept very low. Generally, low cost devices in very small packages, such as TO-92 or SOT, can be used effectively. For fans with nominal operating currents of no more than 200 mA, a single transistor usually suffices. Above 200 mA, the Darlington or MOSFET solution is recommended. For the fan sensing function to work correctly, it is imperative that the pass transistor be fully saturated when "on".

Table 5-2 gives examples of some commonly available transistors and MOSFETs. This table should be used as a guide only since there are many transistors and MOSFETs which will work just as well as those listed. The critical issues when choosing a device to use as Q1 are: (1) the breakdown voltage (V(BR)CEO or V<sub>DS</sub>(MOSFET)) must be large enough to withstand the highest voltage applied to the fan (Note: This will occur when the fan is off); (2) 5 mA of base drive current must be enough to saturate the transistor when conducting the full fan current (transistor must have sufficient gain); (3) the V<sub>OUT</sub> voltage must be high enough to sufficiently drive the gate of the MOSFET to minimize the R<sub>DS(on)</sub> of the device; (4) rated fan current draw must be within the transistor's/MOSFET's current handling capability; and (5) power dissipation must be kept within the limits of the chosen device.

A base-current limiting resistor is required with bipolar transistors. This is shown in Figure 5-6.

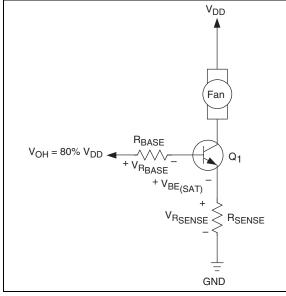


FIGURE 5-6: R<sub>BASE</sub>.

Circuit For Determining

The correct value for this resistor can be determined as follows:

V <sub>OH</sub>	$= V_{RSENSE} + V_{BE(SAT)} + V_{RBASE}$
$V_{RSENSE}$	= I <sub>FAN</sub> x R <sub>SENSE</sub>
$V_{RBASE}$	= R <sub>BASE</sub> x I <sub>BASE</sub>
IBASE	= I <sub>FAN</sub> / h <sub>FE</sub>

 $V_{OH}$  is specified as 80% of  $V_{DD}$  in Section 1.0, "Electrical Characteristics";  $V_{BE(SAT)}$  is given in the chosen transistor data sheet. It is now possible to solve for  $R_{BASE}.$ 

## EQUATION

$$R_{BASE} = \frac{V_{OH} - V_{BE(SAT)} - V_{RSENSE}}{I_{BASE}}$$

Some applications require the fan to be powered from the negative 12V supply to keep motor noise out of the positive voltage power supplies. As shown in Figure 5-8, zener diode D<sub>1</sub> offsets the -12V power supply voltage, holding transistor Q<sub>1</sub> off when V<sub>OUT</sub> is low. When V<sub>OUT</sub> is high, the voltage at the anode of D<sub>1</sub> increases by V<sub>OUT</sub> causing Q<sub>1</sub> to turn on. Operation is otherwise the same as the case of fan operation from +12V.

## TABLE 5-2: TRANSISTORS AND MOSFETS FOR $Q_1 (V_{DD} = 5V)$

			- 00 /		
Package	Max. V <sub>BE(sat)</sub> /V <sub>GS</sub> (V)	Min. H <sub>FE</sub>	V <sub>CEO</sub> /V <sub>DS</sub> (V)	Fan Current (mA)	Suggested R <sub>BASE</sub> (Ω)
SOT-23	1.2	50	40	150	800
TO-92	1.2	50	40	150	800
TO-92	1.2	50	40	500	301
SOT-23	2.5	NA	20	500	Note 1
SOT-23	2.5	NA	20	500	Note 1
SO-8	4.5	NA	30	1000	Note 1
SOT-23	4.5	NA	60	500	Note 1
	Package        SOT-23        TO-92        TO-92        SOT-23        SOT-23        SOT-23        SOT-23	Package      Max. V <sub>BE(sat)</sub> /V <sub>GS</sub> (V)        SOT-23      1.2        TO-92      1.2        TO-92      1.2        SOT-23      2.5        SOT-23      2.5        SOT-23      4.5	Package      Max. V <sub>BE(sat)</sub> /V <sub>GS</sub> (V)      Min. H <sub>FE</sub> SOT-23      1.2      50        TO-92      1.2      50        TO-92      1.2      50        SOT-23      2.5      NA        SOT-23      2.5      NA        SOT-23      4.5      NA	Package      Max. V <sub>BE(sat)</sub> /V <sub>GS</sub> (V)      Min. H <sub>FE</sub> V <sub>CEO</sub> /V <sub>DS</sub> (V)        SOT-23      1.2      50      40        TO-92      1.2      50      40        TO-92      1.2      50      40        SOT-23      2.5      NA      20        SOT-23      2.5      NA      20        SOT-23      4.5      NA      30	Package(V)Mill: HFE(V)(mA)SOT-231.25040150TO-921.25040150TO-921.25040500SOT-232.5NA20500SOT-232.5NA20500SOT-234.5NA301000

Note 1: A series gate resistor may be used in order to control the MOSFET turn-on and turn-off times.

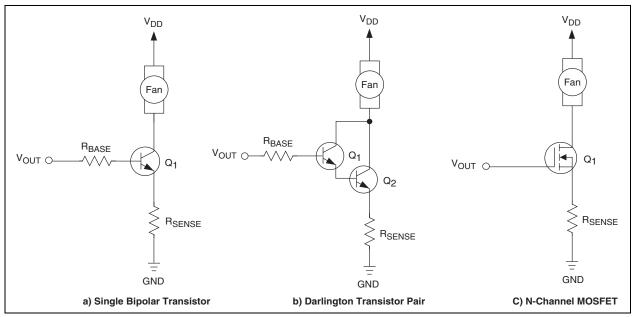
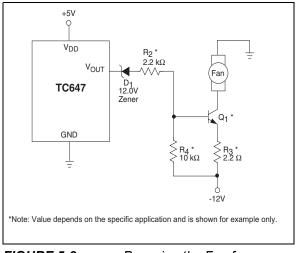


FIGURE 5-7: Output Drive Transistor Circuit Topologies.



*FIGURE 5-8:* Powering the Fan from a -12V Supply.

## 5.6 Latch-Up Considerations

As with any CMOS IC, the potential exists for latch-up if signals are applied to the device which are outside the power supply range. This is of particular concern during power-up if the external circuitry (such as the sensor network,  $V_{MIN}$  divider or shutdown circuit) is powered by a supply different from that of the TC647. Care should be taken to ensure that the TC647's  $V_{DD}$  supply powers up first. If possible, the networks attached to  $V_{IN}$  and  $V_{MIN}$  should connect to the  $V_{DD}$  supply at the same physical location as the IC itself. Even if the IC and any external networks are powered by the same supply, physical separation of the connect-

ing points can result in enough parasitic capacitance and/or inductance in the power supply connections to delay one power supply "routing" versus another.

## 5.7 Power Supply Routing and Bypassing

Noise present on the V<sub>IN</sub> and V<sub>MIN</sub> inputs may cause erroneous operation of the FAULT output. As a result, these inputs should be bypassed with a 0.01  $\mu$ F capacitor mounted as close to the package as possible. This is particularly true of V<sub>IN</sub>, which is usually driven from a high impedance source (such as a thermistor). In addition, the V<sub>DD</sub> input should be bypassed with a 1  $\mu$ F capacitor. Ground should be kept as short as possible. To keep fan noise off the TC647 ground pin, individual ground returns for the TC647 and the low side of the fan current sense resistor should be used.

## **Design Example**

Step 1. Calculate R<sub>1</sub> and R<sub>2</sub> based on using an NTC having a resistance of 10 k $\Omega$  at T<sub>MIN</sub> (25°C) and 4.65 k $\Omega$  at T<sub>MAX</sub> (45°C) (see Figure 5-9). R<sub>1</sub> = 20.5 k $\Omega$ 

 $R_2 = 3.83 \text{ k}\Omega$ 

Step 2. Set minimum fan speed V<sub>MIN</sub> = 1.8V. Limit the divider current to 100  $\mu$ A from which R<sub>5</sub> = 33 k $\Omega$  and R<sub>6</sub> = 18 k $\Omega$ 

Step 3. Design the output circuit.

Maximum fan motor current = 250 mA.  $Q_1$  beta is chosen at 50 from which  $R_7$  = 800 $\Omega$ .

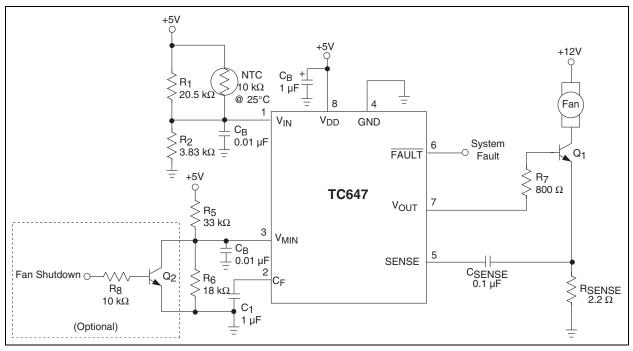


FIGURE 5-9: Design Example.

## 5.8 TC647 as a Microcontroller Peripheral

In a system containing a microcontroller or other host intelligence, the TC647 can be effectively managed as a CPU peripheral. Routine fan control functions can be performed by the TC647 without controller intervention. The microcontroller receives temperature data from one or more points throughout the system. It calculates a fan operating speed based on an algorithm specifically designed for the application at hand. The processor controls fan speed using complimentary port bits I/O1 through I/O3. Resistors  $R_1$  through  $R_6$  (5% tolerance) form a crude 3-bit DAC that translates the 3-bit code from the controller or processor's outputs into a 1.6V DC control signal. A monolithic DAC or digital pot may be used instead of the circuit shown in Figure 5-10.

With V<sub>MIN</sub> set to 1.8V, the TC647 has a minimum operating speed of approximately 40% of full rated speed when the processor's output code is 000[B]. Output codes 001[B] to 111[B] operate the fan from roughly 40% to 100% of full speed. An open-drain output from the processor I/O can be used to reset the TC647 following detection of a fault condition. The FAULT output can be connected to the processor's interrupt input, or to an I/O pin, for polled operation (see Figure 5-10).

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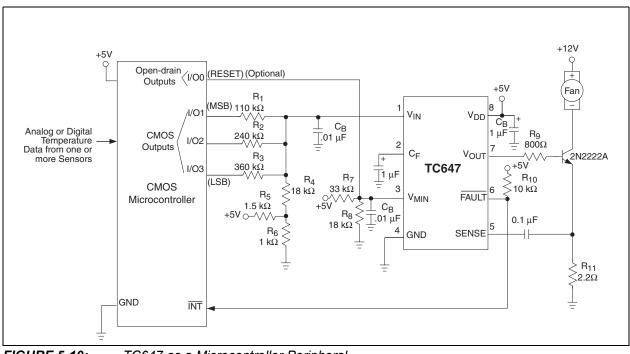
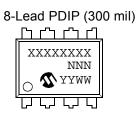


FIGURE 5-10:

TC647 as a Microcontroller Peripheral.

# 6.0 PACKAGING INFORMATION

## 6.1 Package Marking Information

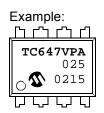


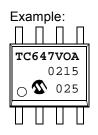
## 8-Lead SOIC (150 mil)

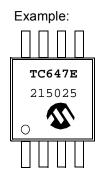


### 8-Lead MSOP





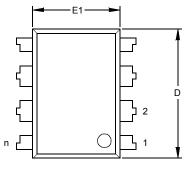


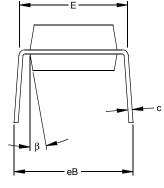


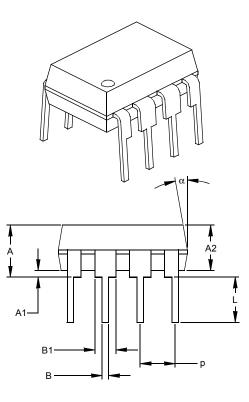
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8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)





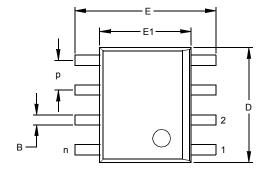


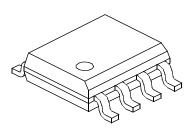
	Units		INCHES*		N	<b>IILLIMETERS</b>	3
Dimension	n Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	А	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

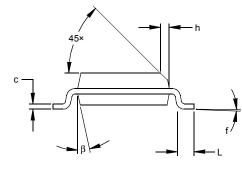
\* Controlling Parameter § Significant Characteristic

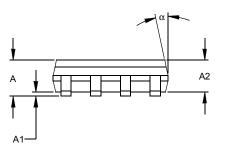
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# 8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)









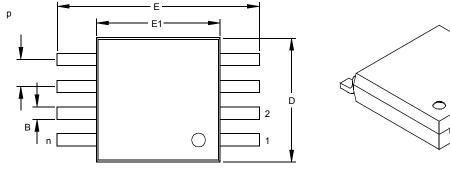
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Dimensi	on Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050			1.27	
Overall Height	А	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	f	0	4	8	0	4	8
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25
Lead Width	В	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

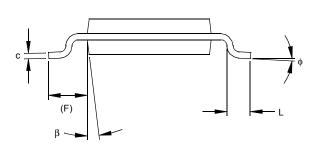
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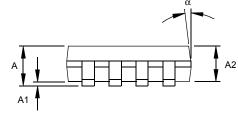
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#### 8-Lead Plastic Micro Small Outline Package (MS) (MSOP) 6.2







	Units		INCHES		М	ILLIMETERS*	
Dimer	nsion Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8				8
Pitch	р		.026			0.65	
Overall Height	А			.044			1.18
Molded Package Thickness	A2	.030	.034	.038	0.76	0.86	0.97
Standoff §	A1	.002		.006	0.05		0.15
Overall Width	E	.184	.193	.200	4.67	4.90	.5.08
Molded Package Width	E1	.114	.118	.122	2.90	3.00	3.10
Overall Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.016	.022	.028	0.40	0.55	0.70
Footprint (Reference)	F	.035	.037	.039	0.90	0.95	1.00
Foot Angle	φ	0		6	0		6
Lead Thickness	С	.004	.006	.008	0.10	0.15	0.20
Lead Width	В	.010	.012	.016	0.25	0.30	0.40
Mold Draft Angle Top	α		7			7	
Mold Draft Angle Bottom	β		7			7	

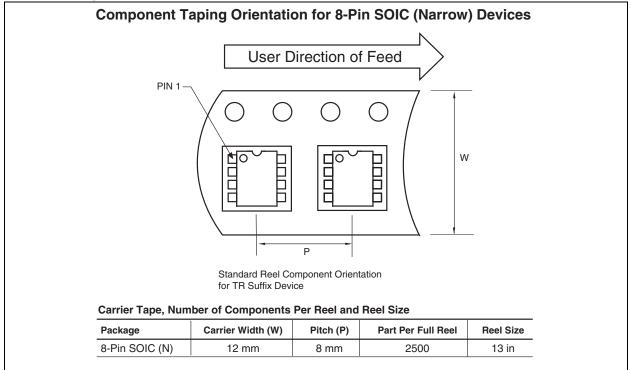
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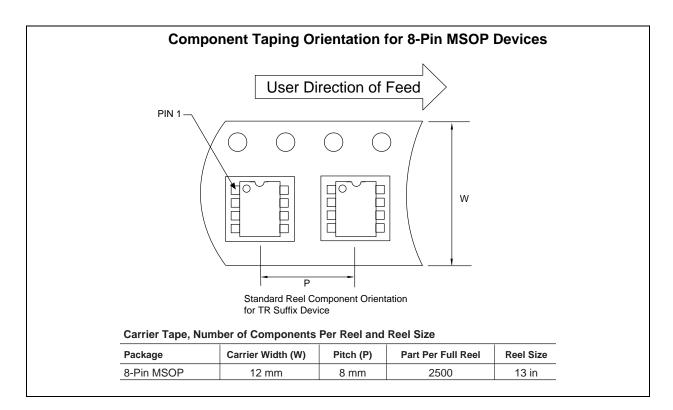
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Device:	TC647: PWM Fan Speed Controller w/Fault Detection	b	) TC647VUA: PWM Fan Speed Controller w/ Fault Detection, MSOP package.
Device.		c)	) TC647VPA: PWM Fan Speed Controller w/ Fault Detection, PDIP package.
Temperature Range:	$V = 0^{\circ}C \text{ to } +85^{\circ}C$ E = -40^{\circ}C to +85^{\circ}C	d	) TC647EOATR: PWM Fan Speed Controller w/Fault Detection, SOIC package, Tape and Reel.
Package:	PA = Plastic DIP (300 mil Body), 8-lead * OA = Plastic SOIC, (150 mil Body), 8-lead UA = Plastic Micro Small Outline (MSOP), 8-lead * PDIP package is only offered in the V temp range		

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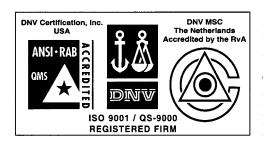
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